

BB02-GQ :- 2.00mm x 2.00mm (0.079" x 0.079") SOCKET, SMD, DUAL ENTRY, DUAL ROW - 06 to 80 CONTACTS

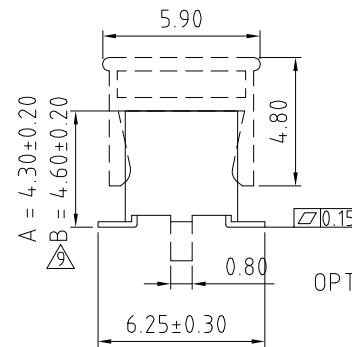
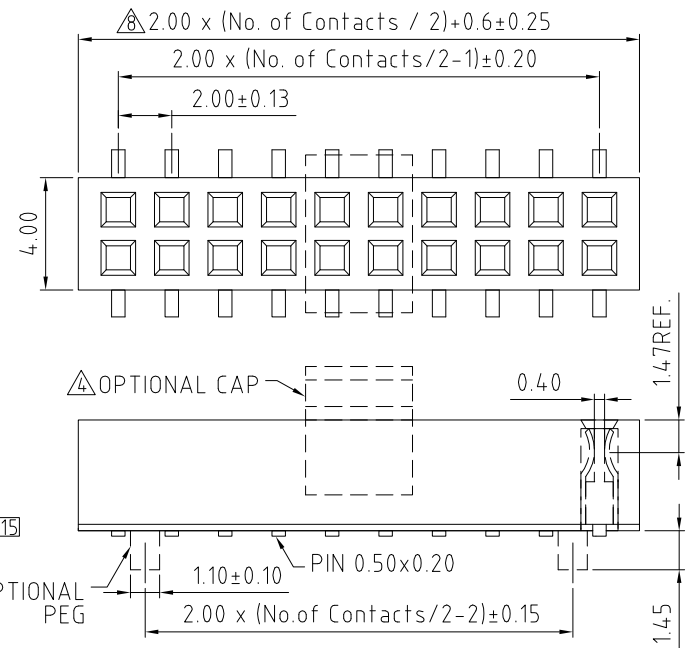
SPECIFICATIONS

CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACT RESISTANCE	20 m ohms MAX
DIELECTRIC WITHSTANDING	500 V AC/DC
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: NYLON 6T
PLATING	GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

MATES WITH :-

BB02-FA	BB02-FQ	BB02-FW
BB02-FD	BB02-FR	BB02-FY
BB02-FE	BB02-FS	BB02-FZ
BB02-FG	BB02-FT	BB02-RH
BB02-FP	BB02-FU	BB02-RN

RECOMMENDED MATING PIN LENGTH FROM TOP ENTRY IS 3.0MM Δ



HOW TO ORDER



NO. OF CONTACTS
06 TO 80

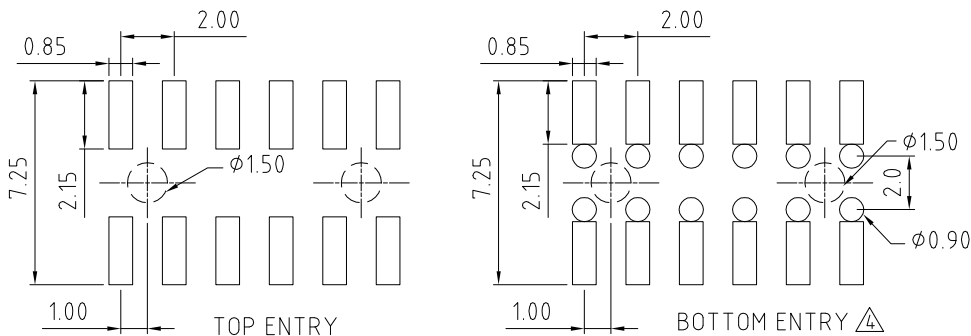
CONNECTOR PROFILE
A = 4.3mm
B = 4.6mm

PACKAGING OPTIONS
3 - TUBE
4 - TUBE & FILM
5 - TUBE & CAP
6 - T & R
7 - T & R & FILM
8 - T & R & CAP

WITH OR WITHOUT LOCATING PEG
A = WITH
B = WITHOUT

CONTACT PLATING OPTIONS Δ Δ

K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL



RECOMMENDED PC BOARD LAYOUT
(TOLERANCE: ±0.05)

REV.	DATE & DRN
10	01/04/05 - NYW RELEASE
11	20/04/05 - NYW
12	10/08/06 - NYW
13	13/02/07 - CHC
14	23/04/07 - NYW
15	26/07/07 - CHC
16	20/05/08 - CHC
17	05/02/09 - CHC
18	08/08/11 - NYW
19	22/02/11 - NYW

Scale:	5:1
Drawn:	CHC
App'd:	XXXX
Date:	22 DEC '11
THIRD ANGLE	
Title	SOCKET
Revision:	1.9

Unstated Tolerances:	
X	± 0.30
.X	± 0.25
.XX	± 0.15
.XXX	± 0.10
Material	SEE NOTE
NOT TO SCALE	
Unit:	mm



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Type:	BB02-GQ
Drawing Number:	BB02-GQ
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